



Microvias: For Low Cost, High Density Interconnects (Electronic Packaging and Interconnection)

John Lau, Ricky Lee

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Microvias: For Low Cost, High Density Interconnects (Electronic Packaging and Interconnection)

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State-of-the-art introduction to high-density interconnect technology

The first-ever book on this hot topic, *Microvias: Low Cost, High Density Interconnects* gives you a thorough look at the technology that's changing the nature of printed circuit boards--and driving the mobile electronic revolution. A "must" for electronics and mechanical engineers, John Lau and Ricky Lee's intensive introduction to microvia technology expertly covers all major techniques. You get important details on mechanical NC drilling, laser drilling, photo-defined, chemical and plasma etching, and conductive ink formation. You also get a survey of the work of leading companies and their products, including Canon, Compaq, Fujitsu Limited, Gore, Hitachi Chemical Co., Ibiden, IBM, JCI, JVC, K&S (X-Lam), Kyocera/JME, Matsushita, Mitsubishi, NEC, Samsung, Sheldahl, Shinko, Toshiba.

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